

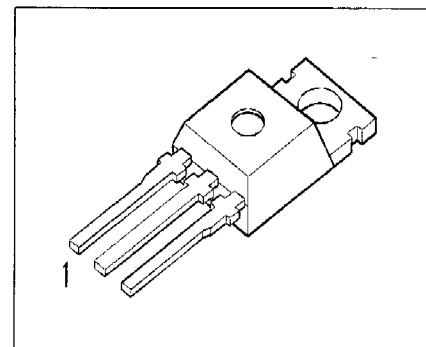
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BUZ 80

- N channel
- Enhancement mode
- Avalanche-rated



Pin 1	Pin 2	Pin 3
G	D	S

Type	V _{DS}	I _D	R _{DS(on)}	Package
BUZ 80	800 V	3.1 A	4 Ω	TO-220 AB

Maximum Ratings

Parameter	Symbol	Values	Unit
Continuous drain current $T_C = 28^\circ\text{C}$	I _D	3.1	A
Pulsed drain current $T_C = 25^\circ\text{C}$	I _{Dpuls}	12.5	
Avalanche current, limited by T_{jmax}	I _{AR}	3.1	
Avalanche energy, periodic limited by T_{jmax}	E _{AR}	8	mJ
Avalanche energy, single pulse $I_D = 3.1 \text{ A}, V_{DD} = 50 \text{ V}, R_{GS} = 25 \Omega$ $L = 62.4 \text{ mH}, T_j = 25^\circ\text{C}$	E _{AS}	320	
Gate source voltage	V _{GS}	± 20	V
Power dissipation $T_C = 25^\circ\text{C}$	P _{tot}	100	W
Operating temperature	T _j	-55 ... + 150	°C
Storage temperature	T _{stg}	-55 ... + 150	
Thermal resistance, chip case	R _{thJC}	≤ 1.25	K/W
Thermal resistance, chip to ambient	R _{thJA}	75	
DIN humidity category, DIN 40 040		E	
IEC climatic category, DIN IEC 68-1		55 / 150 / 56	

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BUZ 80

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Static Characteristics

Drain- source breakdown voltage $V_{GS} = 0 \text{ V}, I_D = 0.25 \text{ mA}, T_j = 25^\circ\text{C}$	$V_{(\text{BR})\text{DSS}}$	800	-	-	V
Gate threshold voltage $V_{GS}=V_{DS}, I_D = 1 \text{ mA}$	$V_{GS(\text{th})}$	2.1	3	4	
Zero gate voltage drain current $V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 25^\circ\text{C}$ $V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 125^\circ\text{C}$	I_{DSS}	-	0.1	1	μA
Gate-source leakage current $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	I_{GSS}	-	10	100	nA
Drain-Source on-resistance $V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$	$R_{DS(\text{on})}$	-	3.5	4	Ω

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Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Dynamic Characteristics

Transconductance $V_{DS} \geq 2 * I_D * R_{DS(on)max}$, $I_D = 2 \text{ A}$	g_{fs}	1	3.6	-	S
Input capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C_{iss}	-	900	1350	pF
Output capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C_{oss}	-	95	140	
Reverse transfer capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$	C_{rss}	-	50	75	
Turn-on delay time $V_{DD} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(on)}$	-	15	25	ns
Rise time $V_{DD} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	t_r	-	65	85	
Turn-off delay time $V_{DD} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	$t_{d(off)}$	-	200	270	
Fall time $V_{DD} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 3 \text{ A}$ $R_{GS} = 50 \Omega$	t_f	-	65	85	

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Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

Reverse Diode

Inverse diode continuous forward current $T_C = 25^\circ\text{C}$	I_S	-	-	3.1	A
Inverse diode direct current,pulsed $T_C = 25^\circ\text{C}$	I_{SM}	-	-	12.5	
Inverse diode forward voltage $V_{GS} = 0 \text{ V}, I_F = 6.2 \text{ A}$	V_{SD}	-	1	1.3	V
Reverse recovery time $V_R = 100 \text{ V}, I_F=I_S, di_F/dt = 100 \text{ A}/\mu\text{s}$	t_{rr}	-	370	-	ns
Reverse recovery charge $V_R = 100 \text{ V}, I_F=I_S, di_F/dt = 100 \text{ A}/\mu\text{s}$	Q_{rr}	-	2.5	-	μC